



SOT778-4

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 x 6 x 0.85 mm

19 July 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package outline version code	SOT778-4
Manufacturer package code	SOT778
Package type industry code	HVQFN
Package outline version description	plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 x 6 x 0.85 mm
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	IC26_CHAPTER_6_2000
Mounting method type	S (surface mount)
Specific mounting and soldering information	HVQFN_mounting.pdf
Generic mounting and soldering information	AN10365
Major version date	9-10-2008
Minor version date	14-5-2012
Security status	COMPANY PUBLIC
Modified date	14-5-2012
Issue date	12-7-2016
Web publication date	28-11-2012
Initial web publication date	18-1-2011
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	-	-	0.85	-	mm
A	seated height	-	-	0.85	1	mm
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	48	-	

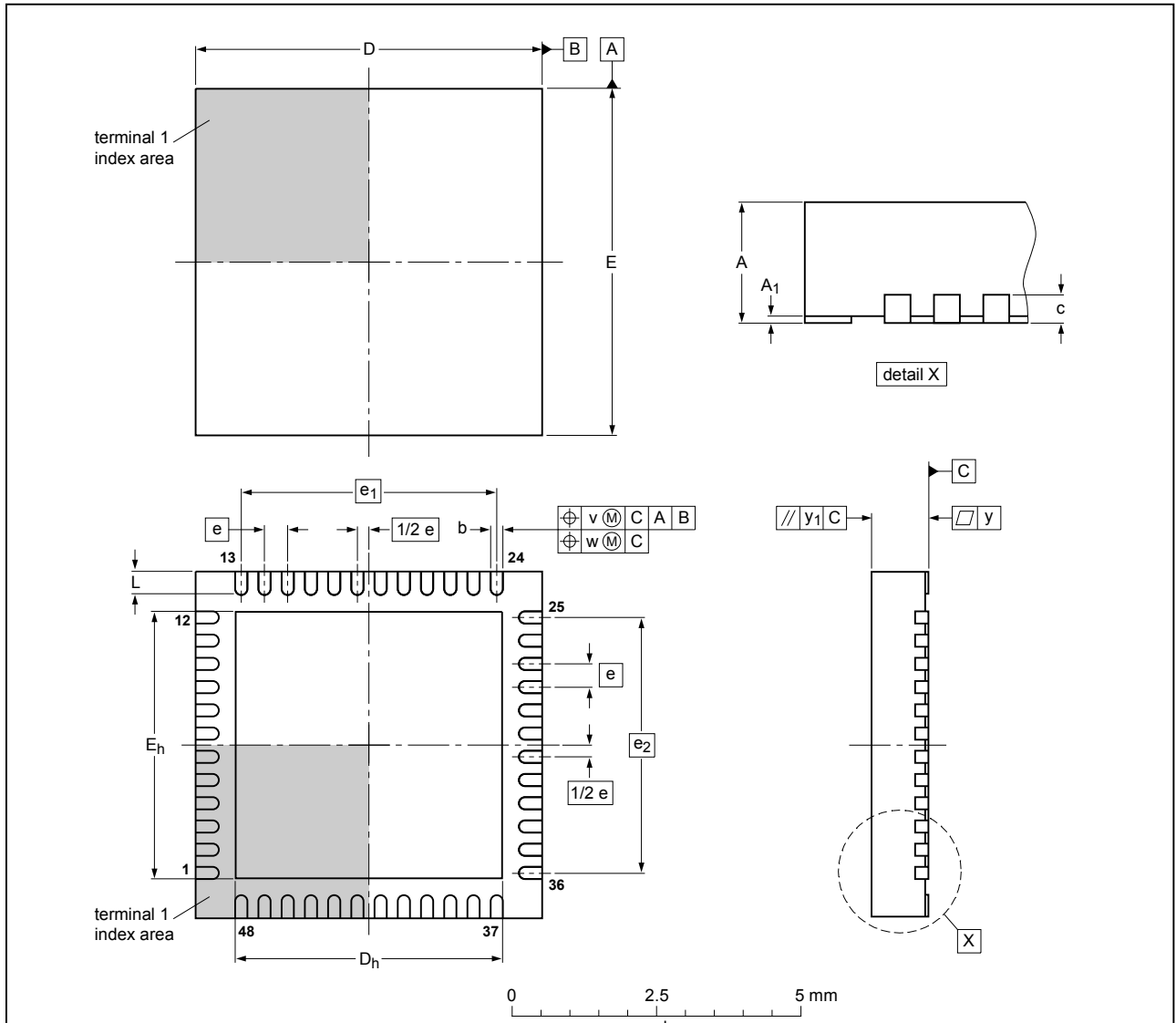


plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 x 6 x 0.85 mm

2. Package outline

HVQFN48: plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 x 6 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.25 0.15	0.2	6.1 5.9	4.75 4.45	6.1 5.9	4.75 4.45	0.4	4.4	4.4	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT778-4	---	---	---			-04-07-30- 04-10-07

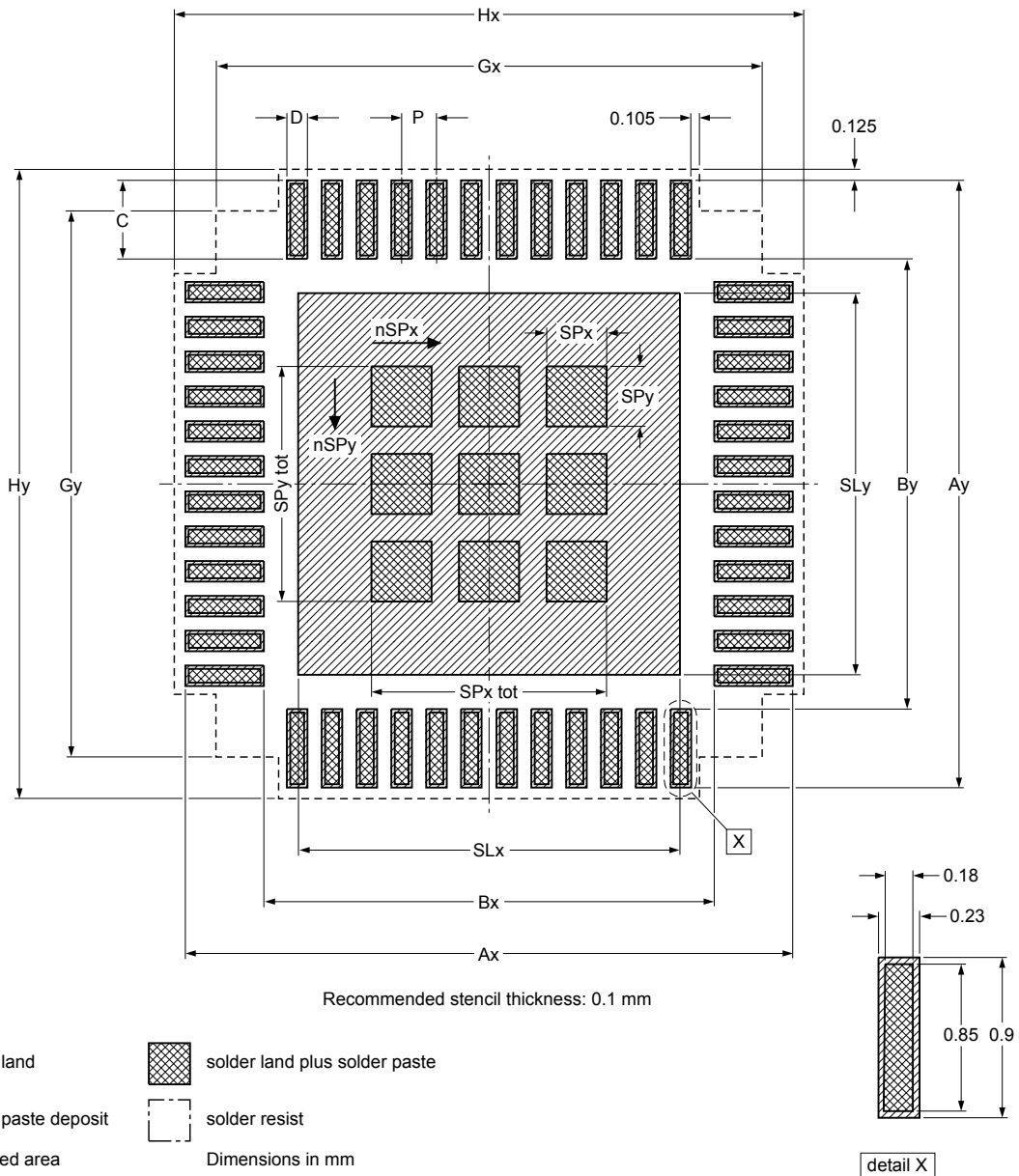
Fig. 1. Package outline HVQFN (SOT778-4)

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3. Soldering

Footprint information for reflow soldering of HVQFN48 package

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Dimensions (mm are the original dimensions)

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy	nSPx	nSPy
0.4	7.0	7.0	5.2	5.2	0.9	0.23	4.4	4.4	2.7	2.7	0.7	0.7	6.3	6.3	7.25	7.25	3	3

Issue date ~~16-07-11~~
16-07-12

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Fig. 2. Reflow soldering footprint for HVQFN (SOT778-4)

4. Legal information

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